



(12) **Patent Application Publication**
SHIH et al.

(43) **Pub. Date:** **Jun. 27, 2024**

Publication Classification

(51) **Int. Cl.**
H05K 1/02 (2006.01)
H05K 1/11 (2006.01)

(52) **U.S. Cl.**
CPC *H05K 1/0271* (2013.01); *H05K 1/0298*
(2013.01); *H05K 1/115* (2013.01); *H05K*
2201/09827 (2013.01)

(57) **ABSTRACT**

The present disclosure provides an electronic device and a method of manufacturing the same. The electronic device includes a first redistribution structure and a first encapsulant. The first encapsulant supports the first redistribution structure and is configured to function as a first reinforcement to provide a second redistribution structure. The redistribution structure has a plurality of conductive layers disposed over the first redistribution structure.

(22) Filed: **Dec. 21, 2022**

